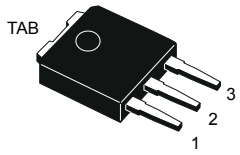
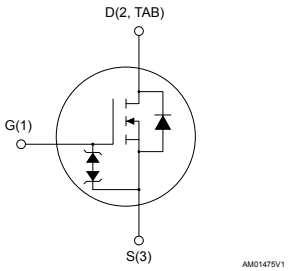
STU5N70M6-S

Datasheet

N-channel 700 V, 1.2 Ω typ., 3.5 A MDmesh™ M6 Power MOSFET in a short IPAK package



Short IPAK



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STU5N70M6-S	700 V	1.4 Ω	3.5 A

- Reduced switching losses
- Lower $R_{DS(on)}$ per area vs previous generation
- Low gate input resistance
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

The new MDmesh™ M6 technology incorporates the most recent advancements to the well-known and consolidated MDmesh family of SJ MOSFETs. STMicroelectronics builds on the previous generation of MDmesh devices through its new M6 technology, which combines excellent $R_{DS(on)}$ per area improvement with one of the most effective switching behaviors available, as well as a user-friendly experience for maximum end-application efficiency.

Product status link
STU5N70M6-S

Product summary	
Order code	STU5N70M6-S
Marking	5N70M6
Package	Short IPAK
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±25	V
I_D	Drain current (continuous) at T_C = 25 °C	3.5	A
	Drain current (continuous) at T_C = 100 °C	2.2	A
I_{DM}(1)	Drain current pulsed	8	A
P_{TOT}	Total dissipation at T_C = 25 °C	45	W
dv/dt(2)	Peak diode recovery voltage slope	5	V/ns
dv/dt(3)	MOSFET dv/dt ruggedness	50	
T_j	Operating junction temperature range	-55 to 150	°C
T_{stg}	Storage temperature range		

1. *Pulse width limited by safe operating area*
2. *I_{SD} ≤ 3.5 A, di/dt ≤ 400 A/µs, V_{DS} peak ≤ $V_{(BR)DSS}$, V_{DD} = 100 V*
3. *V_{DS} ≤ 560 V*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	2.78	°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient	100	°C/W

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	1	A
E_{AS}	Single-pulse avalanche energy (starting T_J = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	77	mJ

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 4. On-/off-states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	700			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 700 V			1	µA
		V_{GS} = 0 V, V_{DS} = 700 V T_C = 125 °C(1)			100	µA
I_{GSS}	Gate body leakage current	V_{DS} = 0 V, V_{GS} = ±25 V			±5	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2.25	3	3.75	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 1.75 A		1.2	1.4	Ω

1. *Defined by design, no subject to production test.*

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 100 V, V_{GS} = 0 V, f = 1 MHz	-	170	-	pF
C_{oss}	Output capacitance		-	15	-	pF
C_{rss}	Reverse transfer capacitance		-	1	-	pF
$C_{oss\ eq.}$(1)	Equivalent output capacitance	V_{DS} = 0 to 560 V, V_{GS} = 0 V	-	70	-	pF
R_g	Intrinsic gate resistance	f = 1 MHz, open drain	-	5	-	Ω
Q_g	Total gate charge	V_{DD} = 350 V, I_D = 1 A V_{GS} = 0 to 10 V (see Figure 14. Test circuit for gate charge behavior)	-	5.1	-	nC
Q_{gs}	Gate-source charge		-	0.85	-	nC
Q_{gd}	Gate-drain charge		-	2.6	-	nC

1. *$C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.*

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 350 V, I_D = 1.75 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	5.8	-	ns
t_r	Rise time		-	6.5	-	ns
$t_{d(off)}$	Turn-off delay time		-	17	-	ns
t_f	Fall time		-	27.5	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		3.5	A
I_{SDM}(1)	Source-drain current (pulsed)		-		8	A
V_{SD}(2)	Forward on-voltage	I_{SD} = 3.5 A, V_{GS} = 0 V	-		1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 3.5 A, V_{DD} = 60 V, di/dt = 100 A/µs (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	230		ns
Q_{rr}	Reverse recovery charge		-	1.25		µC
I_{RRM}	Reverse recovery current		-	11		A
t_{rr}	Reverse recovery time	I_{SD} = 3.5 A, V_{DD} = 60 V, di/dt = 100 A/µs, T_j = 150 °C (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	277		ns
Q_{rr}	Reverse recovery charge		-	1.4		µC
I_{RRM}	Reverse recovery current		-	10		A

1. *Pulse width limited by safe operating area*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

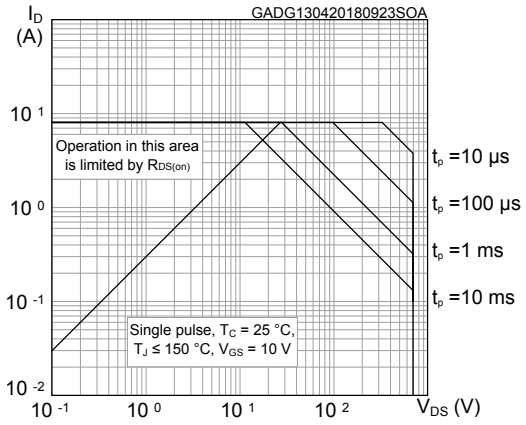


Figure 2. Thermal impedance

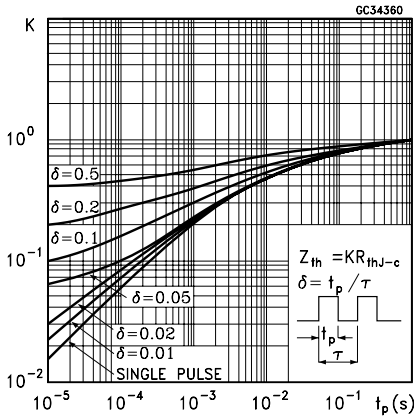


Figure 3. Output characteristics

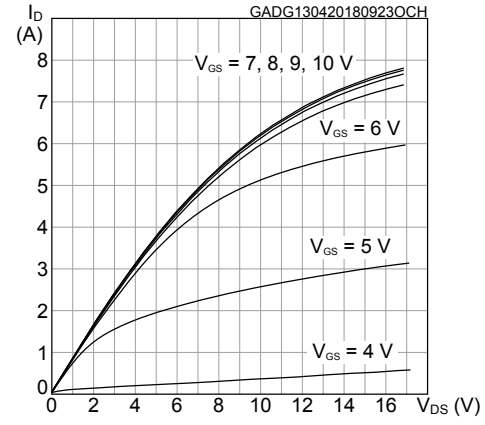


Figure 4. Transfer characteristics

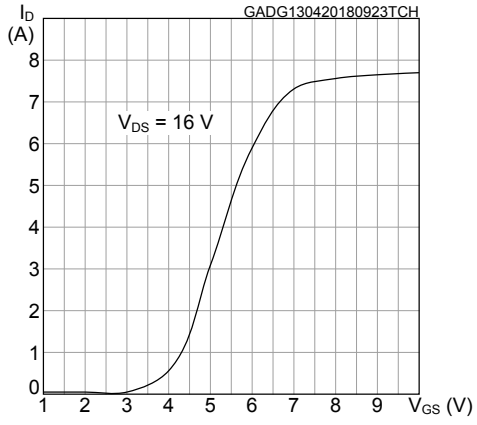


Figure 5. Gate charge vs gate-source voltage

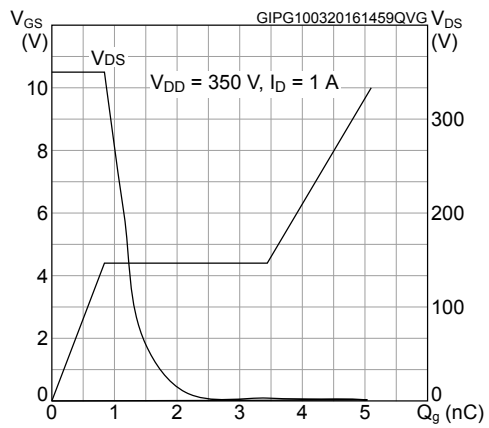


Figure 6. Static drain-source on-resistance

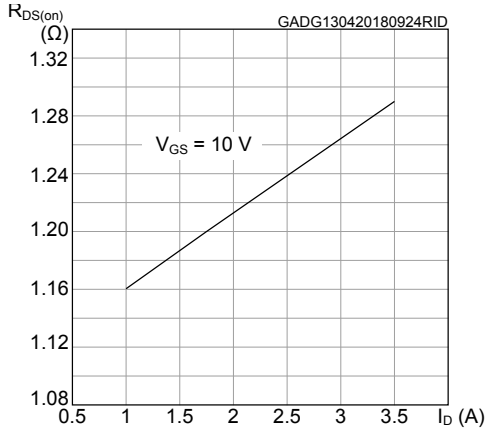


Figure 7. Capacitance variations

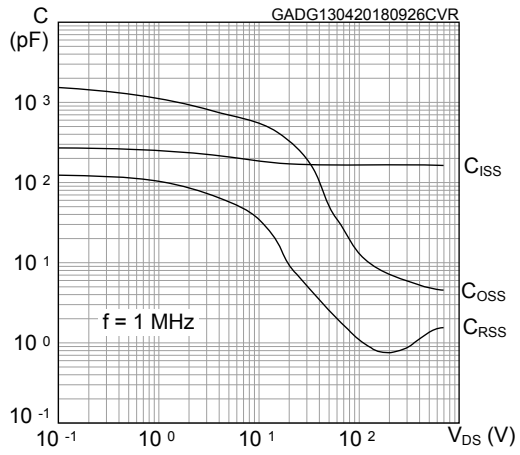


Figure 8. Normalized gate threshold voltage vs temperature

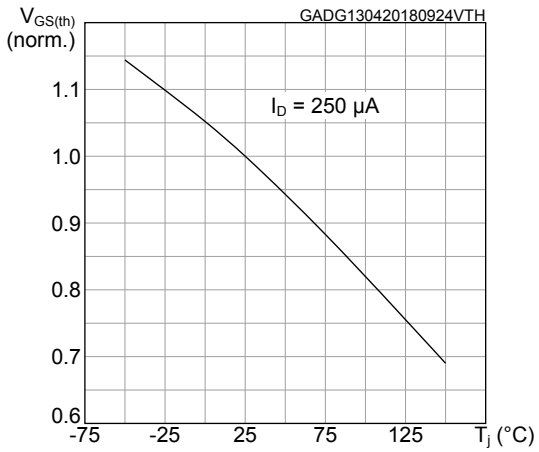


Figure 9. Normalized on-resistance vs temperature

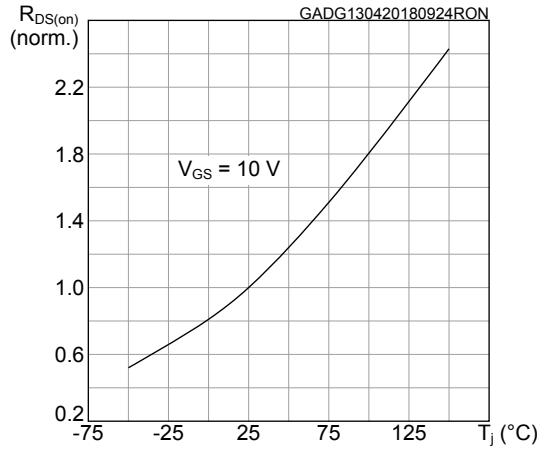


Figure 10. Normalized $V_{(BR)DSS}$ vs temperature

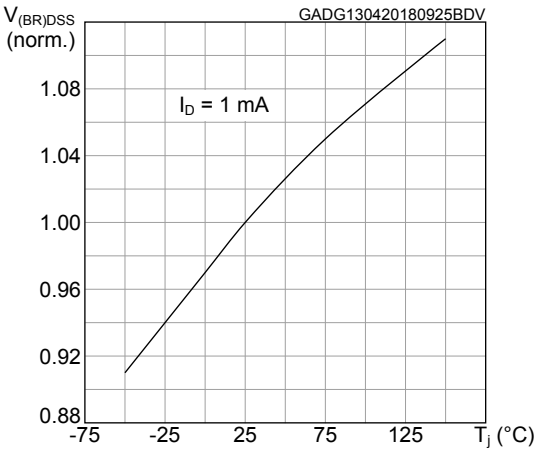


Figure 11. Output capacitance stored energy

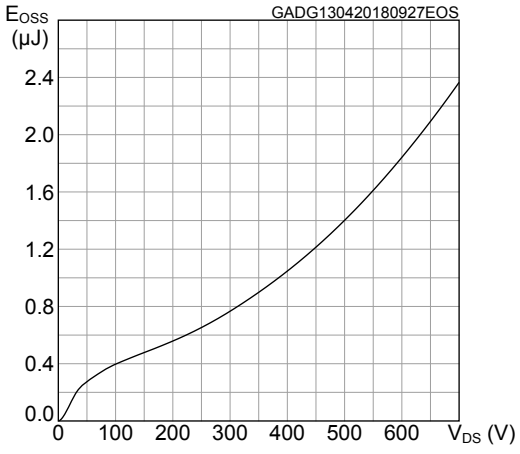
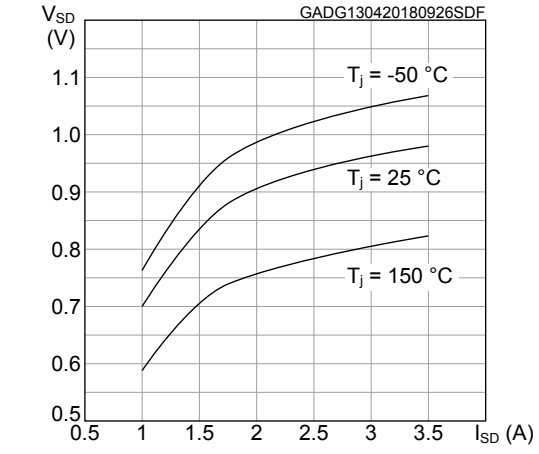


Figure 12. Source-drain forward characteristics



3 Test circuits

Figure 13. Test circuit for resistive load switching times

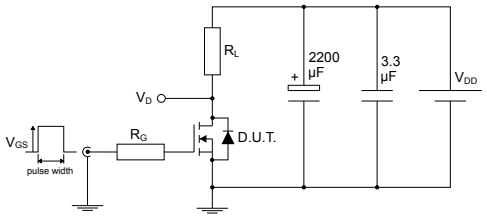


Figure 14. Test circuit for gate charge behavior

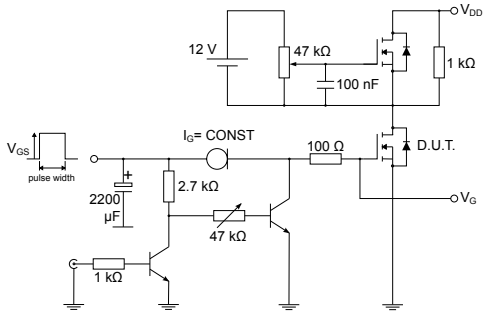


Figure 15. Test circuit for inductive load switching and diode recovery times

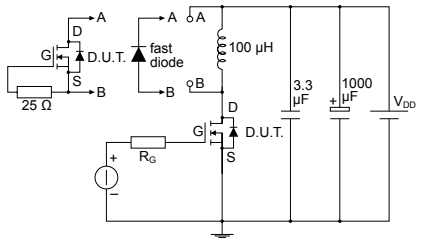


Figure 16. Unclamped inductive load test circuit

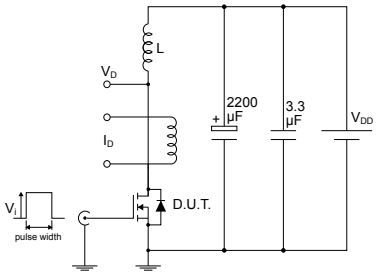


Figure 17. Unclamped inductive waveform

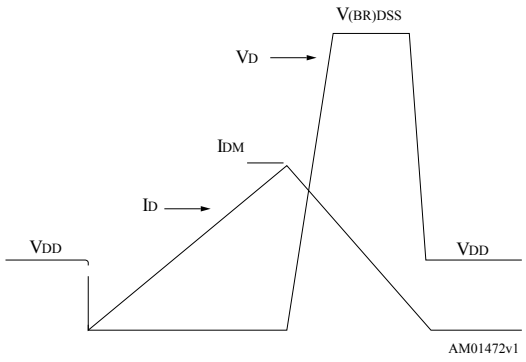
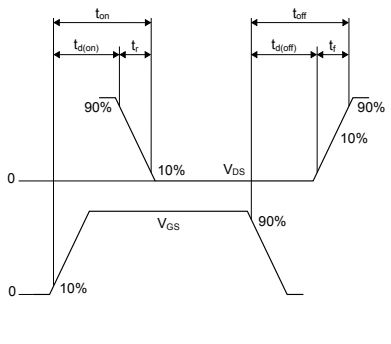


Figure 18. Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 Short IPAK package information

Figure 19. **Short IPAK package outline**

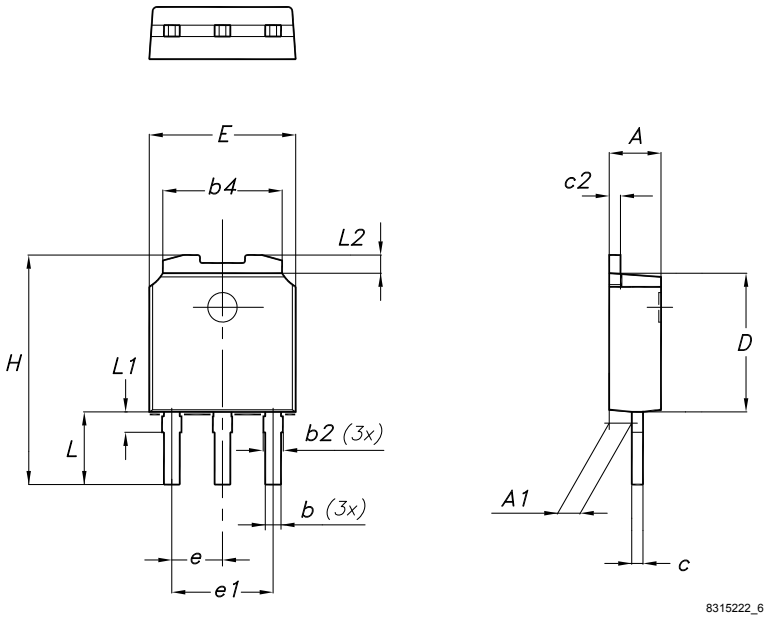


Table 8. **Short IPAK package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.35
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.15
E	6.40		6.55
e		2.25	
e1	4.40		4.60
H	9.80		10.40
L	3.00		3.40
L1	0.80		1.20
L2		0.80	1.00

Revision history

Table 9. **Document revision history**

Date	Version	Changes
09-May-2018	1	Initial release. The document status is production data.

Contents